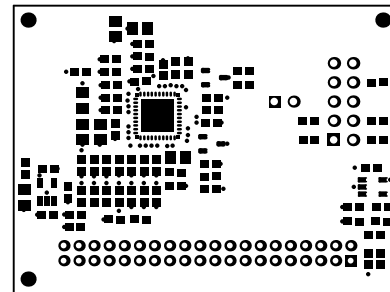
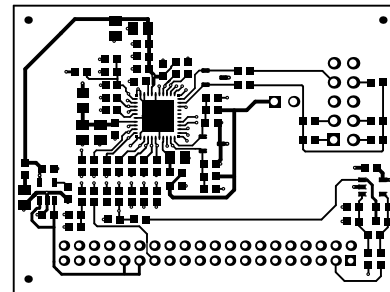


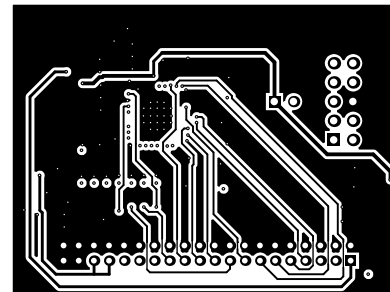
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11432ControlCard A	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP11432	
PLOT NAME = Top Overlay	GENERATED : 1/6/2016 1:47:54 PM	TEXAS INSTRUMENTS



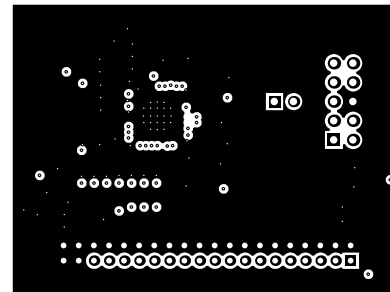
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11432ControlBoard A	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP11432	
PLOT NAME = Top Solder Mask	GENERATED : 1/6/2016 1:47:56 PM	TEXAS INSTRUMENTS



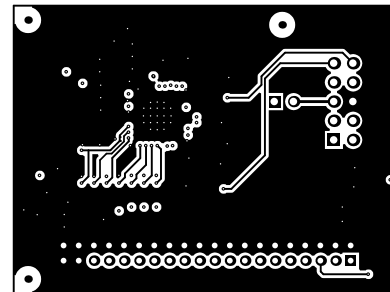
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11432ControlBoard A	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP11432	
PLOT NAME = Top Layer	GENERATED : 1/6/2016 1:47:57 PM	TEXAS INSTRUMENTS



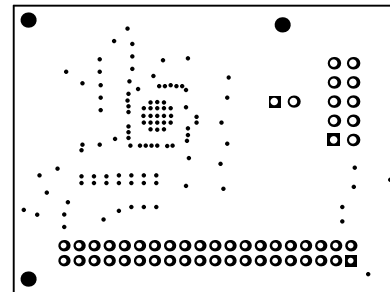
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11432Control Board A	SVN REV: Not In VersionControl
LAYER NAME = Signal Layer 1	TID #: PMP11432	
PLOT NAME = Signal Layer 1	GENERATED : 1/6/2016 1:47:58 PM	TEXAS INSTRUMENTS



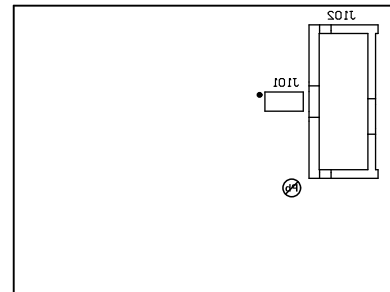
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11432Control Board A	SVN REV: Not In VersionControl
LAYER NAME = Signal Layer 2	TID #: PMP11432	
PLOT NAME = Signal Layer 2	GENERATED : 1/6/2016 1:47:59 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11432ControlBoard A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP11432	
PLOT NAME = Bottom Layer	GENERATED : 1/6/2016 1:48:00 PM	TEXAS INSTRUMENTS

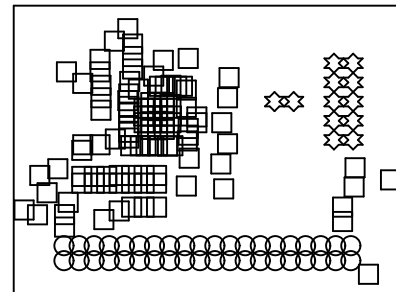


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11432Control Board A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP11432	
PLOT NAME = Bottom Solder Mask	GENERATED : 1/6/2016 1:48:02 PM	TEXAS INSTRUMENTS

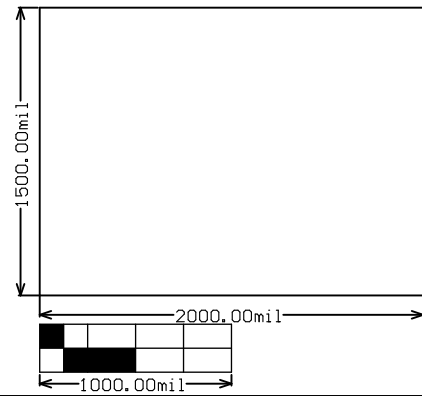


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11432Control Board A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP11432	
PLOT NAME = Bottom Overlay	GENERATED : 1/6/2016 1:48:03 PM	TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
□	109	8.00mil (0.203mm)	PTH	Round
○	40	31.00mil (0.787mm)	PTH	Round
✱	12	46.00mil (1.016mm)	PTH	Round
	161 Total			



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11432ControlRev A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP11432	
PLOT NAME = Drill Drawing	GENERATED : 1/6/2016 1:48:04 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11432Control Board A	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP11432	
PLOT NAME = Board Dimensions	GENERATED : 1/6/2016 1:48:05 PM	TEXAS INSTRUMENTS

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